



Product Change Notification / ALAN-13SUCS155

Date:

15-Jul-2022

Product Category:

PoE PSE, Reverse Power Feed

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4826 Final Notice: Qualification of TJS5 as an additional fabrication site for PD69208T4ILQ-TR-LE, PD81101ILQ-TR-LE, PD69208MILQ-TR-LE, PD69204T4ILQ-TR-LE, and PD39208ILQ-TR-LE catalog part numbers (CPN) in 56L VQFN (8x8x1.0mm) package.

Affected CPNs:

[ALAN-13SUCS155_Affected_CPN_07152022.pdf](#)

[ALAN-13SUCS155_Affected_CPN_07152022.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of TJS5 as an additional fabrication site for PD69208T4ILQ-TR-LE, PD81101ILQ-TR-LE, PD69208MILQ-TR-LE, PD69204T4ILQ-TR-LE, and PD39208ILQ-TR-LE catalog part numbers (CPN) in 56L VQFN (8x8x1.0mm) package.

Pre and Post Change Summary:

	Pre Change	Post Change
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Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:November 24, 2021: Issued initial notification.

June 14, 2022: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on June 28, 2022.

July 15, 2022: Re-issued final notification. Updated change impact. Revised pre and post change summary in PCN letter and added the Pre and post change summary in ppt file.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[Modification-to-AN3361-and-AN3615-Reference-Design-00004588B.pdf](#)

[PCN ALAN-13SUCS155 Qualification Report.pdf](#)

[PCN_ALAN-ALAN-13SUCS155_Pre and Post Change_Summary.pdf](#)

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PD69208/PD69204/PD39208

Implications of Adding TowerJazz 5 as Alternative Manufacture Site

Introduction

Microchip manufactures PD6920x and PD39208 devices using wafers from TowerJazz Fab 2 (TJ2) located in Migdal HaEmek, Israel. To bring additional capacity, the PD6920x and PD39208 devices will be manufactured using wafers from TowerJazz Fab 5 (TJ5) in Arai, Japan. This manufacturing change is documented in [PCN ALAN-13SUCS155](#).

1. Reference Designs

The application note *AN3361 Designing an IEEE® 802.3af/at/bt PoE System Based on PD692x0/PD69208* (www.microchip.com/DS00003361) provides detailed information and circuitry design guidelines for the implementation of a Power over Ethernet (PoE) Power Source Equipment (PSE) system, based on Microchip's PD69208T4, PD69204T4, or PD69208M PoE Managers and PD69210, PD69220 or PD69200 PoE Controllers. Application note *AN3615 Designing an IEEE® 802.3af/at PoE System Based on PD39210 + PD39208 Chipset* (www.microchip.com/DS00003615) is the equivalent application note for the Microchip PD39210 + PD39208 Chipset.

With the introduction of the PD6920x and PD39208 TJ5 material, there is a minor change to the Application Schematic and BOM. Component C36 is changed from a 0.1 μF capacitor to a 17.4 k Ω resistor. This resistor has a Reference Designator R52. This change is mandatory for TJ5 material and optional for TJ2 material. There is no performance degradation in making this change for TJ2 material. Either the 0.1 μF capacitor or the 17.4 k Ω resistor can be used for TJ2 material with no detrimental effect.

It is recommended to make this component change on all platforms to accommodate both TJ2 and TJ5 materials.

1.1 Physical PCB Implications

C36 is a 0.1 μF 10V X7R, 0402 capacitor. C36 is connected from the VAUX5 pin of the IC to analog ground. It will be replaced by R52 which is a 17.4 k Ω 1% 0402 resistor. As both components are 0402, R52 is a "drop in" replacement for C36. There is no critical implication on the PCB design or manufacturing process.

2. Identification of TJ2 and TJ5 Material

The following sections describe the two methods to identify TJ2 and TJ5 material:

- By inspection of the physical package marking.
- Through the 16-byte communication protocol.

2.1 Physical Package Marking

The following figure shows that the TJ2 material is marked “LE” where TJ5 material is marked “ZZ”.

Figure 2-1. Package Markings



2.2 16-Byte Protocol

For IEEE[®] 802.3bt firmware, see section 3.2.2 Get BT PoE Device Status in the *BT Serial Communication Protocol User Guide*. For IEEE 802.3at/af firmware, see section 4.2.2 Get PoE Device Status in the *Serial Communication Protocol User Guide*. These documents can be found in [Microchips Software Library](#).

The following figure shows the “bt” version.

Figure 2-2. Get BT PoE Device Status

[0]	[1]	[2]	[3]	[4]	[5]	[6]	[7]	[8]	[9]	[10]	[11]	[12]
KEY	ECHO	SUB	SUB1	SUB2	DATA	DATA	DATA	DATA	DATA	DATA	DATA	DATA
0x02	##	0x07	0xD3	Val	0x4E	0x4E	0x4E	0x4E	0x4E	0x4E	0x4E	0x4E
Request	—	Global	BT Device Info	CNum	N	N	N	N	N	N	N	N
0x03	##	Val	Val	Val	Val	Val	Val	Val	Val	Val	Val	Val
Telemetry	—	CNum	PoE Device-Version	Device Status	Device Event	Device Found	MCHP Use8	Temperature [Celsius]	TSH [Celsius]	Reset/POR Counters	N	N

- V2R4 is 0x4A02
- V2R5 is 0x5BC2

3. Revision History

Revision	Date	Description
B	06/2022	<p>The following is the summary of changes made in this revision:</p> <ul style="list-style-type: none"> • Changed the document title from <i>Modification to AN3361 and AN3615 Reference Design</i> to <i>Implications of Adding TowerJazz 5 as Alternative Manufacture Site</i>. • Added 2. Identification of TJ2 and TJ5 Material section. • Added information to 1. Reference Designs section.
A	05/2022	Initial Revision

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QUALIFICATION REPORT SUMMARY

PCN #: ALAN-13SUCS155

Date:
May 31, 2022

Qualification of TJS5 as an additional fabrication site for PD69208T4ILQ-TR-LE, PD81101ILQ-TR-LE, PD69208MILQ-TR-LE, PD69204T4ILQ-TR-LE, and PD39208ILQ-TR-LE catalog part numbers (CPN) in 56L VQFN (8x8x1.0mm) package.

I. Summary:

Qualification of TJS5 as an additional fabrication site for PD69208T4ILQ-TR-LE, PD81101ILQ-TR-LE, PD69208MILQ-TR-LE, PD69204T4ILQ-TR-LE, and PD39208ILQ-TR-LE catalog part numbers (CPN) in 56L VQFN (8x8x1.0mm) package.

II. Device Description:

Device	PD69208M
Mask	VJH11
MSL	5579
Product Description	IEEE 802.3at / bt Type 3 8 ports, Fully Integrated PSE Manager, Industrial Temp.
Document Control Number	ML0520220084
Document Revision	A

III. Qualification Material:

Test / Lot	Lot 1	Lot 2	Lot 3
DEVICE	PD69208M V2R5	PD69208M V2R5	PD69208M V2R5
MASK, REV	VJH11; Rev A4	VJH11; Rev A4	VJH11; Rev A4
WAFER FAB	TPSCo Japan	TPSCo Japan	TPSCo Japan
WAFER LOT	EBPN691701AP	EBPN691801AP	TJS5922302674.100
ASSEMBLY LOT	EBPN691701AP-4	EBPN691801AP-4	NSEB224300484.000
TRACE CODE	1728TAB	1729TAE	22034CM
PACKAGE	56L VQFN 8x8x1.0mm	56L VQFN 8x8x1.0mm	56L VQFN 8x8x1.0mm
ASSEMBLY SITE	NSEB-THAILAND	NSEB-THAILAND	NSEB-THAILAND
TEST LOCATION	Garden Grove, CA-USA		
QUAL PROJECT#	42025-1	42025-2	42025-3
QUAL TESTS	HTOL, PRECOND, HTSL, HAST, UHAST, TC, PCA (Package Construction Analysis).	HTOL, PRECOND, HTSL, HAST, UHAST, TC.	HTOL, ESD.

BOM TABLE

Misc.	Assembly site	NSEB
	BD Number	D-034107/B
	MP Code (MPC)	VJH11T5HCA07
	Part Number (CPN)	PD69208MILQ-TR-LE
	MSL information	MSL-1/260
	Assembly Shipping Media (T/R, Tube/Tray)	Tray
	Base Quantity Multiple (BQM)	2000
	Reliability Site	N/A
	CCB No	4826
Lead-Frame	Paddle size	272x272 mils
	Material	C194
	DAP Surface Prep	NiPdAu
	Treatment	No
	Process	Etched
	Lead-lock	Yes
	Part Number	FR1165
	Lead Plating	NiPdAu-PPF
	Strip Size	250x70 mm
Strip Density	175 units/strip	
Bond Wire	Material	CuPdAu
Die Attach	Part Number	590-4HT1
	Conductive	Yes
MC	Part Number	G700LTD
PKG	PKG Type	VQFN
	Pin/Ball Count	56
	PKG width/size	8x8x1.0mm

IV. Qualification Data:

High Temperature Operating Life (HTOL):

Test Method/ Condition	JESD22, Method 108, Tj = + 130°C, VCC = +57.0V, 1000 HR		
Lot #	Results (Fail/SS)		Minimum SS = 77
Lot 1: EBPN691701AP-4	0/80 @168hrs	0/80 @500hrs	0/80 @1000hrs
Lot 2: EBPN691801AP-4	0/80 @168hrs	0/80 @500hrs	0/80 @1000hrs
Lot 3: NSEB224300484.000	0/80 @168hrs	0/80 @500hrs	0/80 @1000hrs

Pre and Post testing was conducted at +25°C, -40°C & +85°C.

ESD-HBM/CDM

Test	Reference Method	Fail/Pass	Result
HBM	JEDEC JS-001	\pm 500V 0/3 \pm 1000V 0/3 \pm 1500V 0/3 \pm 2000V 0/3	Pass \pm 2000V
CDM	AEC-Q100-011	\pm 250V 0/3 \pm 500V 0/3 \pm 750V 0/3 \pm 1000V 0/3	Pass \pm 1000V

Pre and Post testing was conducted at +25°C.

Package Preconditioning:

Test Method/Condition	JEDEC J-STD-020 / JESD22-A113, MSL1 (+85°C/85%RH) 168hours, 3x Reflow @ +260°C (+0/-5C) Peak Reflow Temperature.	
Lot #	Results (Fail/SS)	Minimum SS = 246
Lot 1: EBPN691701AP-4	0/266	CSAM/PASS
Lot 2: EBPN691801AP-4	0/266	CSAM/PASS

Pre and Post testing was conducted at +25°C and +85°C.

HTSL (High Temperature Storage Life)

Test Method/Condition	JESD22-A113 @ MSL1, 3x IR @ +260°C; JESD22-A103, Ta = +150 °C, 1000 HRS.		
Lot #	Results (Fail/SS)	Minimum SS = 25	
Lot 1: EBPN691701AP-4	0/25	CSAM/PASS	
Lot 2: EBPN691801AP-4	0/25	CSAM/PASS	

Pre and Post testing was conducted at +25°C & +85°C.

HAST (Highly Accelerated Temperature and Humidity Stress Test)

Test Method/Condition	JESD22-A113 @ MSL1, 3x IR @ +260°C; JESD22-A110, Vin = +33.5 V, Ta = +130°C/85%RH, 192 HRS.		
Lot #	Results (Fail/SS)	Minimum SS = 20	
Lot 1: EBPN691701AP-4	0/20 @96hrs 0/20 @192hrs	CSAM/PASS	
Lot 2: EBPN691801AP-4	0/20 @96hrs 0/20 @192hrs	CSAM/PASS	

Pre and Post testing was conducted at +25°C & +85°C.

TC (Temperature Cycling)

Test Method/Condition	JESD22-A113 @ MSL1, 3x IR @ +260°C; JESD22-A104, Test Condition C, (-65C / +150C), 1000 Cycles.		
Lot #	Results (Fail/SS)	Minimum SS = 77	
Lot 1: EBPN691701AP-4	0/77	CSAM/PASS	WBP/PASS
Lot 2: EBPN691801AP-4	0/77	CSAM/PASS	

Pre and Post testing was conducted at +25°C & +85°C.

UHASt (Un-bias HAST)

Test Method/Condition	JESD22-A113 @ MSL1, 3x IR @ +260°C; UHASt JESD22 A118 (Ta =+130°C/85% RH) 192 hours.
Lot #	Results (Fail/SS)
Lot 1: EBPN691701AP-4	0/77 @96hrs 0/77 @192hrs
Lot 2: EBPN691801AP-4	0/77 @96hrs 0/77 @192hrs

Pre and Post testing was conducted at +25°C.

PCA (Package Construction Analysis) reference FA#2022-00926

Test Method/Condition	Zero-hour decap and visual inspection.
Lot #	Results
Lot 1: EBPN691701AP-4	PASS

V. Conclusion:

Based on the results, the PD69208M, mask# VJH11 complies with the reliability guidelines in Microchip. Therefore, this part can be released to production.

CCB 4826
Pre and Post Change Summary
PCN# ALAN-13SUCS155



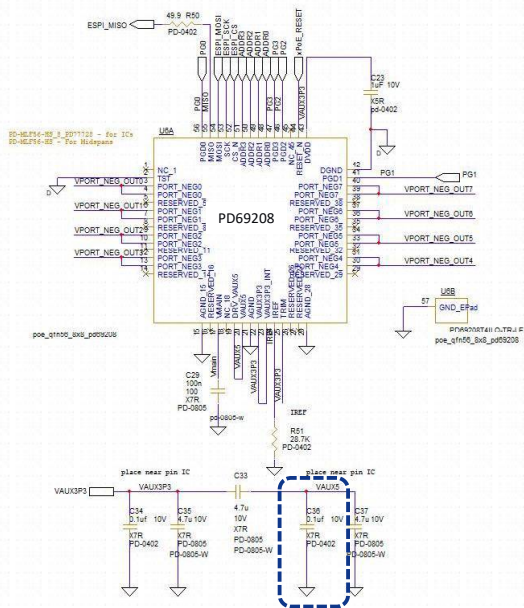
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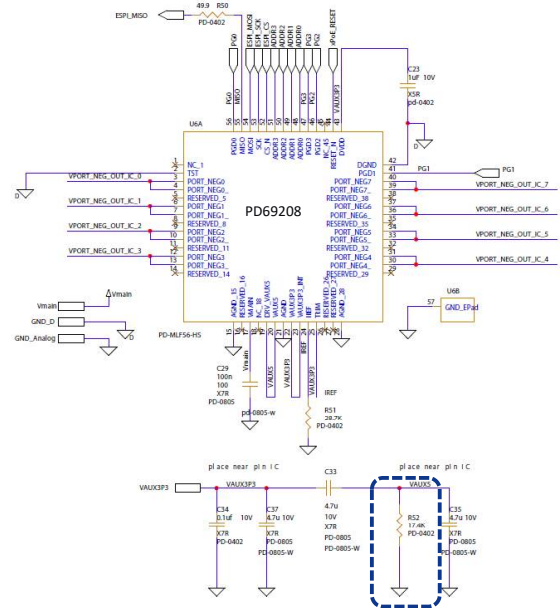
SMART | CONNECTED | SECURE

Pre and Post Change Summary

TJM2



TJM2 and TJS5



2 *Note: Same component footprint, no PCB change required.



ALAN-13SUCS155 - CCB 4 PD81101IL PD69208M PD69204T and PD39208ILQ-TR-LE catalog part numbers

Affected Catalog Part Numbers(CPN)

PD69208T4ILQ-TR-LE

PD81101ILQ-TR-LE

PD69208MILQ-TR-LE

PD69204T4ILQ-TR-LE

PD39208ILQ-TR-LE